

AMENDMENTS TO THE SPECIFICATION

In the Specification

Please replace paragraph [0037] beginning on page 16 with the following amended paragraph:

[0037] Some practitioners may find it appropriate to include one or more surfactants in the composition. The surfactants, which are optional, may tend to help improve the wettability of the resist, for example during immersion lithography, development, or both. However, it is contemplated that at least a portion of the surfactants may, at least potentially, contribute to scum. In one aspect, the attachment of the hydroxyl or other hydrophilic group to the protecting group may be useful to reduce the amount of surfactant. In one embodiment of the invention, exposing the layer to the radiation may include wetting the hydrophilic group of the detached group with an immersion lithography fluid. In one embodiment of the invention, wetting the hydrophilic group with the fluid may include forming a hydrogen bond between a hydroxyl group and the fluid. In various aspects, the surfactants may be employed at concentrations of from about 0 to 10wt%, 0 to 5wt%, or 0 to 1 wt%.